

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	6318	"plasma torch"	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/24 10:52
L2	774	("plasma torch" or "plasma jet") with (wafer or substrate)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/24 10:52
L3	51	"plasma torch" same (wafer or substrate) same (etch\$4 or remov\$4)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/24 10:54
L4	448	"plasma torch" and (wafer or substrate) and (etch\$4 or remov\$4) and deposit\$3	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/24 10:55
L5	30	4 and "438"/\$.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/24 10:55
L6	490	("plasma torch" or "plasma jet") same (polish\$4 or etch\$4 or clean\$4)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/24 10:59
L9	106	("plasma torch" or "plasma jet") same (polish\$4 or etch\$4 or clean\$4) same (wafer or substrate)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/24 10:58
L10	471	("plasma torch" or "plasma jet") and (polish\$4 or etch\$4 or clean\$4) and atmospheric	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/24 11:00
L11	13	("plasma torch" or "plasma jet") and (polish\$4 or etch\$4 or clean\$4) and atmospheric and (RIE or "reactive ion etching")	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/24 11:00